Specification of Thermoelectric Module

TEHC1-12712S

Description

The 127 couples, 40 mm \times 40 mm size single module which is made of our high performance ingot to achieve superior cooling performance and 74°C or larger delta Tmax, is designed for superior cooling and heating applications. Beyond the standard below, we can design and manufacture the custom made module according to your special requirements.

Features

- High effective cooling and efficiency
- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly, RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

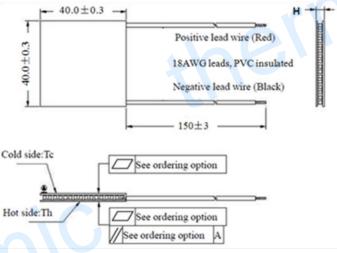
Performance Specification Sheet

Application

- Food and beverage service refrigerator
- Portable cooler box for cars
- Temperature stabilizer
- Liquid cooling
- CPU cooler and scientific instrument
- Photonic and medical systems

Th (°C)	27	50	Hot side temperature at environment: dry air, N ₂	
DT _{max} (°C)	74	83	Temperature Difference between cold and hot side of the module	
			when cooling capacity is zero at cold side 📃 🦯	
U _{max} (Voltage)	16.8	18.09	Voltage applied to the module at DT _{max}	
I _{max} (Amps)	11.5	11.5	DC current through the modules at DT _{max}	
Q _{Cmax} (Watts)	122.6	134.3	Cooling capacity at cold side of the module under DT=0 °C	
AC resistance (Ohms)	1.1	1.22	The module resistance is tested under AC	
Tolerance (%)	± 10		For thermal and electricity parameters	

Geometric Characteristics Dimensions in millimeters



Manufacturing Options

A. Solder:	B. Sealant:		
1. T100: BiSn (Tmelt=138°C)	1. NS: No sealing (Standard)		
2. T200: CuAgSn (Tmelt = 217°C)	2. SS: Silicone sealant		
3. T240: SbSn (Tmelt = 240°C)	3. EPS: Epoxy sealant		
C. Ceramics:	D. Ceramics Surface Options:		
1. Alumina (Al ₂ O ₃ , white 96%)	1. Blank ceramics (not metalized)		
2. Aluminum Nitride (AlN)	2. Metalized		

Ordering Option

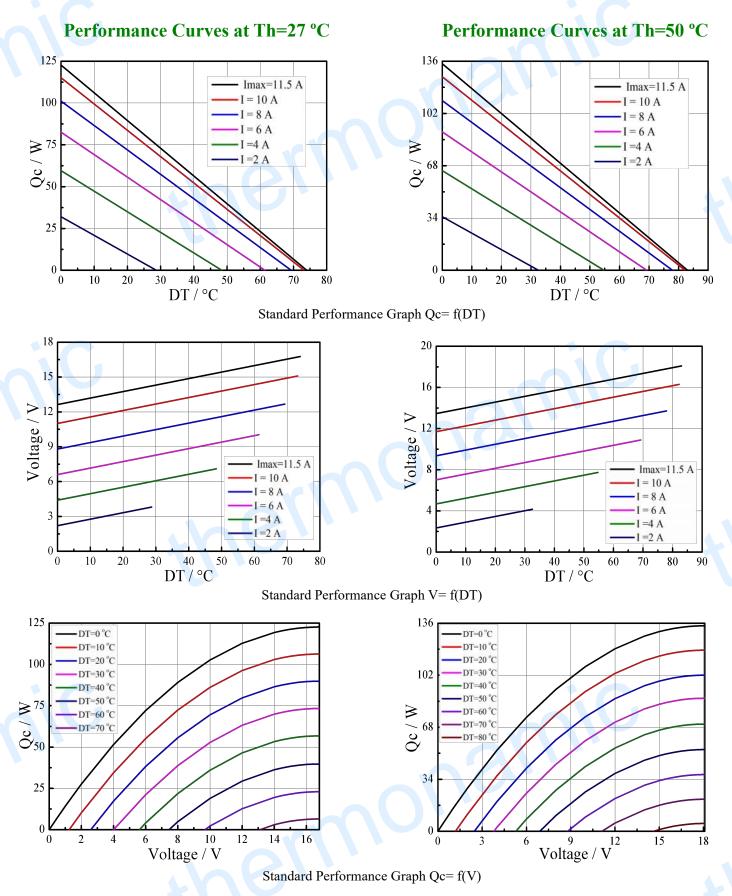
Naming for the Module

Suffix	Thickness H / (mm)	Flatness/Lead wire length (mmParallelism (mm)Standard/Optional length		TEHC1-12712S-X-X-X-X	
TF	0:3.2±0.1	0:0.08/0.08	150±3/Specify	Flatness/Parallelism Sealant	
TF	1:3.2±0.03	1:0.03/0.03	150±3/Specify	Solder TEHC1-12712S-T100-NS -TF01 -AIO	
Eg. TF01: Thickness 3.2±0.1(mm) and Flatness 0.03/0.03(mm)				T100: BiSn (Tmelt=138°C) NS: No sealing	AlO: Alumina (Al2O3, white 96%

Creative technology with fine manufacturing processes provides you the reliable and quality products Tel: +86-791-88198288 Fax: +86-791-88198308 Email: <u>sales@thermonamic.com.cn</u> Web Site: www.thermonamic.com.cn

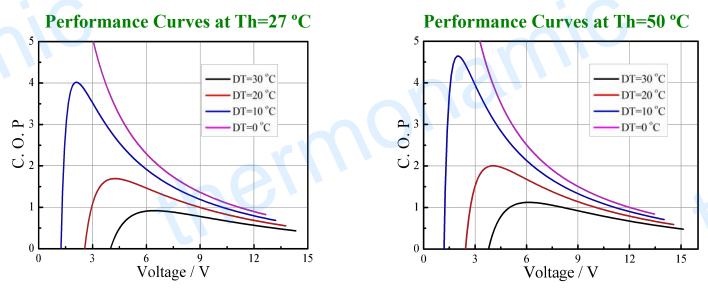
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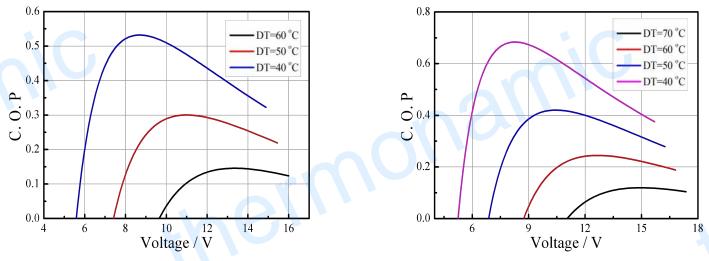


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Standard Performance Graph COP = f(V) of DT ranged from 0 to 30 °C



Standard Performance Graph COP = f(V) of DT ranged from 40 to 60/70 °C

Remark: The coefficient of performance (COP) is the cooling power Qc/Input power (V × I).

Operation Cautions

- Attach the cold side of module to the object to be cooled
- Attach the hot side of module to a heat radiator for heat dissipating menc
- Operation below I_{max} or V_{max}
- Work under DC